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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I ² C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	3K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 10x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LFQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f100gddfb-30

O ROM, RAM capacities

Flash ROM	Data flash	RAM	RL78/G13					
			20 pins	24 pins	25 pins	30 pins	32 pins	36 pins
128 KB	8 KB	12 KB	—	—	—	R5F100AG	R5F100BG	R5F100CG
	—		—	—	—	R5F101AG	R5F101BG	R5F101CG
96 KB	8 KB	8 KB	—	—	—	R5F100AF	R5F100BF	R5F100CF
	—		—	—	—	R5F101AF	R5F101BF	R5F101CF
64 KB	4 KB	4 KB Note	R5F1006E	R5F1007E	R5F1008E	R5F100AE	R5F100BE	R5F100CE
	—		R5F1016E	R5F1017E	R5F1018E	R5F101AE	R5F101BE	R5F101CE
48 KB	4 KB	3 KB Note	R5F1006D	R5F1007D	R5F1008D	R5F100AD	R5F100BD	R5F100CD
	—		R5F1016D	R5F1017D	R5F1018D	R5F101AD	R5F101BD	R5F101CD
32 KB	4 KB	2 KB	R5F1006C	R5F1007C	R5F1008C	R5F100AC	R5F100BC	R5F100CC
	—		R5F1016C	R5F1017C	R5F1018C	R5F101AC	R5F101BC	R5F101CC
16 KB	4 KB	2 KB	R5F1006A	R5F1007A	R5F1008A	R5F100AA	R5F100BA	R5F100CA
	—		R5F1016A	R5F1017A	R5F1018A	R5F101AA	R5F101BA	R5F101CA

Flash ROM	Data flash	RAM	RL78/G13							
			40 pins	44 pins	48 pins	52 pins	64 pins	80 pins	100 pins	128 pins
512 KB	8 KB	32 KB Note	—	R5F100FL	R5F100GL	R5F100JL	R5F100LL	R5F100ML	R5F100PL	R5F100SL
	—		—	R5F101FL	R5F101GL	R5F101JL	R5F101LL	R5F101ML	R5F101PL	R5F101SL
384 KB	8 KB	24 KB	—	R5F100FK	R5F100GK	R5F100JK	R5F100LK	R5F100MK	R5F100PK	R5F100SK
	—		—	R5F101FK	R5F101GK	R5F101JK	R5F101LK	R5F101MK	R5F101PK	R5F101SK
256 KB	8 KB	20 KB Note	—	R5F100FJ	R5F100GJ	R5F100JJ	R5F100LJ	R5F100MJ	R5F100PJ	R5F100SJ
	—		—	R5F101FJ	R5F101GJ	R5F101JJ	R5F101LJ	R5F101MJ	R5F101PJ	R5F101SJ
192 KB	8 KB	16 KB	R5F100EH	R5F100FH	R5F100GH	R5F100JH	R5F100LH	R5F100MH	R5F100PH	R5F100SH
	—		R5F101EH	R5F101FH	R5F101GH	R5F101JH	R5F101LH	R5F101MH	R5F101PH	R5F101SH
128 KB	8 KB	12 KB	R5F100EG	R5F100FG	R5F100GG	R5F100JG	R5F100LG	R5F100MG	R5F100PG	—
	—		R5F101EG	R5F101FG	R5F101GG	R5F101JG	R5F101LG	R5F101MG	R5F101PG	—
96 KB	8 KB	8 KB	R5F100EF	R5F100FF	R5F100GF	R5F100JF	R5F100LF	R5F100MF	R5F100PF	—
	—		R5F101EF	R5F101FF	R5F101GF	R5F101JF	R5F101LF	R5F101MF	R5F101PF	—
64 KB	4 KB	4 KB Note	R5F100EE	R5F100FE	R5F100GE	R5F100JE	R5F100LE	—	—	—
	—		R5F101EE	R5F101FE	R5F101GE	R5F101JE	R5F101LE	—	—	—
48 KB	4 KB	3 KB Note	R5F100ED	R5F100FD	R5F100GD	R5F100JD	R5F100LD	—	—	—
	—		R5F101ED	R5F101FD	R5F101GD	R5F101JD	R5F101LD	—	—	—
32 KB	4 KB	2 KB	R5F100EC	R5F100FC	R5F100GC	R5F100JC	R5F100LC	—	—	—
	—		R5F101EC	R5F101FC	R5F101GC	R5F101JC	R5F101LC	—	—	—
16 KB	4 KB	2 KB	R5F100EA	R5F100FA	R5F100GA	—	—	—	—	—
	—		R5F101EA	R5F101FA	R5F101GA	—	—	—	—	—

Note The flash library uses RAM in self-programming and rewriting of the data flash memory.

The target products and start address of the RAM areas used by the flash library are shown below.

R5F100xD, R5F101xD (x = 6 to 8, A to C, E to G, J, L): Start address FF300H

R5F100xE, R5F101xE (x = 6 to 8, A to C, E to G, J, L): Start address FEF00H

R5F100xJ, R5F101xJ (x = F, G, J, L, M, P): Start address FAF00H

R5F100xL, R5F101xL (x = F, G, J, L, M, P, S): Start address F7F00H

For the RAM areas used by the flash library, see **Self RAM list of Flash Self-Programming Library for RL78 Family (R20UT2944)**.

Table 1-1. List of Ordering Part Numbers

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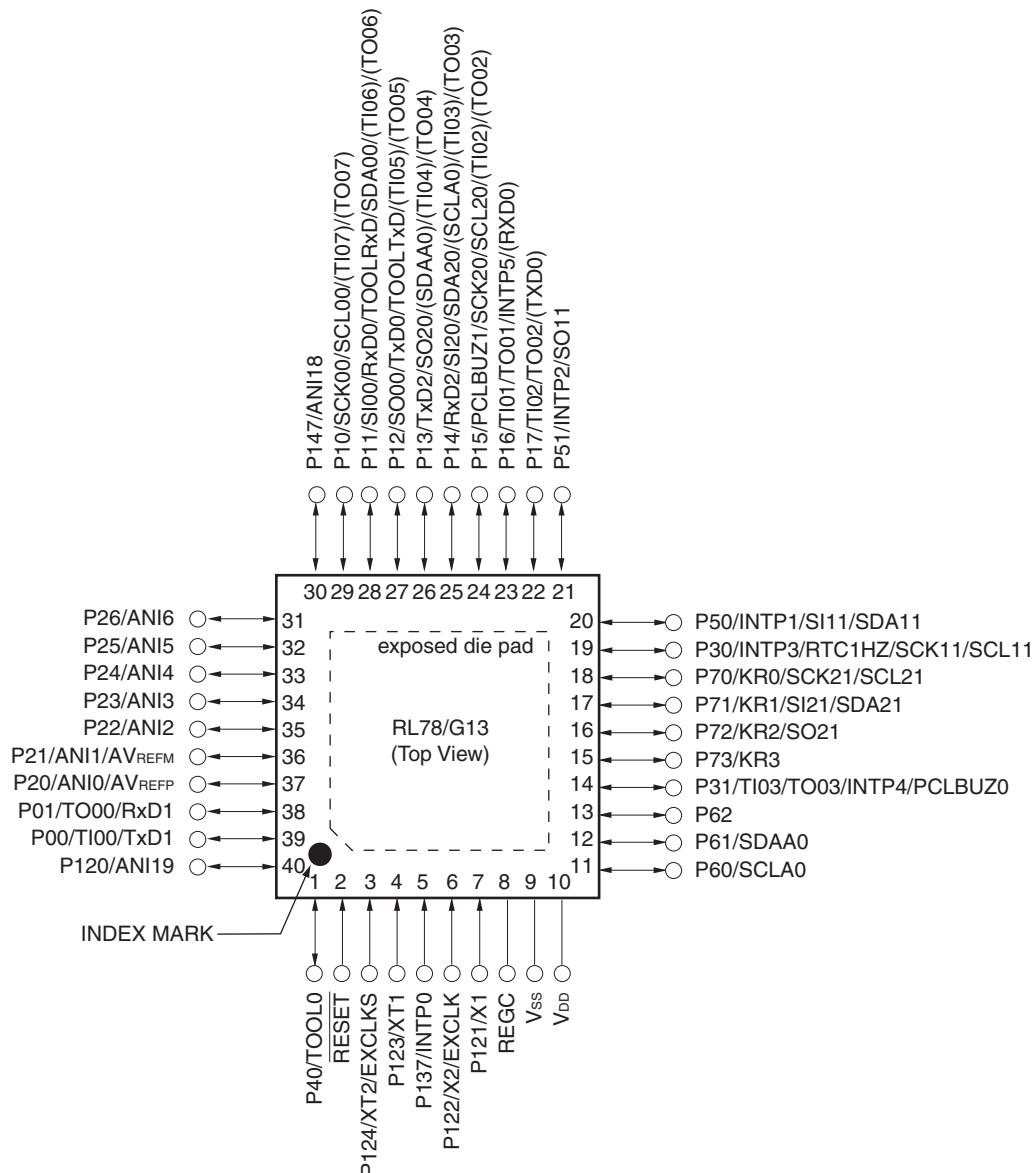
Pin count	Package	Data flash	Fields of Application <small>Note</small>	Ordering Part Number
48 pins	48-pin plastic HWQFN (7 × 7 mm, 0.5 mm pitch)	Mounted	A D G	R5F100GAANA#U0, R5F100GCANA#U0, R5F100GDANA#U0, R5F100GEANA#U0, R5F100GFANA#U0, R5F100GGANA#U0, R5F100GHANA#U0, R5F100GJANA#U0, R5F100GKANA#U0, R5F100GLANA#U0 R5F100GAANA#W0, R5F100GCANA#W0, R5F100GDANA#W0, R5F100GEANA#W0, R5F100GFANA#W0, R5F100GGANA#W0, R5F100GHANA#W0, R5F100GJANA#W0, R5F100GKANA#W0, R5F100GLANA#W0 R5F100GADNA#U0, R5F100GCDNA#U0, R5F100GDDNA#U0, R5F100GEDNA#U0, R5F100GFDNA#U0, R5F100GGDNA#U0, R5F100GHDNA#U0, R5F100GJDNA#U0, R5F100GKDNA#U0, R5F100GLDNA#U0 R5F100GADNA#W0, R5F100GCDNA#W0, R5F100GDDNA#W0, R5F100GEDNA#W0, R5F100GFDNA#W0, R5F100GGDNA#W0, R5F100GHDNA#W0, R5F100GJDNA#W0, R5F100GKDNA#W0, R5F100GLDNA#W0 R5F100GAGNA#U0, R5F100GCGNA#U0, R5F100GDGNA#U0, R5F100GEGNA#U0, R5F100GFGNA#U0, R5F100GGGNA#U0, R5F100GHGNA#U0, R5F100GJGNA#U0 R5F100GAGNA#W0, R5F100GCGNA#W0, R5F100GDGNA#W0, R5F100GEGNA#W0, R5F100GFGNA#W0, R5F100GGGNA#W0, R5F100GHGNA#W0, R5F100GJGNA#W0
	Not mounted	A D		R5F101GAANA#U0, R5F101GCANA#U0, R5F101GDANA#U0, R5F101GEANA#U0, R5F101GFANA#U0, R5F101GGANA#U0, R5F101GHANA#U0, R5F101GJANA#U0, R5F101GKANA#U0, R5F101GLANA#U0 R5F101GAANA#W0, R5F101GCANA#W0, R5F101GDANA#W0, R5F101GEANA#W0, R5F101GFANA#W0, R5F101GGANA#W0, R5F101GHANA#W0, R5F101GJANA#W0, R5F101GKANA#W0, R5F101GLANA#W0 R5F101GADNA#U0, R5F101GCDNA#U0, R5F101GDDNA#U0, R5F101GEDNA#U0, R5F101GFDNA#U0, R5F101GGDNA#U0, R5F101GHDNA#U0, R5F101GJDNA#U0, R5F101GKDNA#U0, R5F101GLDNA#U0 R5F101GADNA#W0, R5F101GCDNA#W0, R5F101GDDNA#W0, R5F101GEDNA#W0, R5F101GFDNA#W0, R5F101GGDNA#W0, R5F101GHDNA#W0, R5F101GJDNA#W0, R5F101GKDNA#W0, R5F101GLDNA#W0

Note For the fields of application, refer to **Figure 1-1 Part Number, Memory Size, and Package of RL78/G13**.

Caution The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.

1.3.7 40-pin products

- 40-pin plastic HWQFN (6 × 6 mm, 0.5 mm pitch)



Caution Connect the REGC pin to V_{ss} via a capacitor (0.47 to 1 μ F).

Remarks 1. For pin identification, see **1.4 Pin Identification**.

2. Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.
3. It is recommended to connect an exposed die pad to V_{ss}.

3. The number of PWM outputs varies depending on the setting of channels in use (the number of masters and slaves) (see **6.9.3 Operation as multiple PWM output function** in the RL78/G13 User's Manual).
4. When setting to PIOR = 1

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Item	20-pin		24-pin		25-pin		30-pin		32-pin		36-pin	
	R5F1006x	R5F1016x	R5F1007x	R5F1017x	R5F1008x	R5F1018x	R5F1004Ax	R5F101Ax	R5F100Bx	R5F101Bx	R5F100Cx	R5F101Cx
Clock output/buzzer output	–		1		1		2		2		2	
	<ul style="list-style-type: none"> • 2.44 kHz, 4.88 kHz, 9.76 kHz, 1.25 MHz, 2.5 MHz, 5 MHz, 10 MHz (Main system clock: f_{MAIN} = 20 MHz operation) 											
8/10-bit resolution A/D converter	6 channels		6 channels		6 channels		8 channels		8 channels		8 channels	
Serial interface	<p>[20-pin, 24-pin, 25-pin products]</p> <ul style="list-style-type: none"> • CSI: 1 channel/simplified I²C: 1 channel/UART: 1 channel • CSI: 1 channel/simplified I²C: 1 channel/UART: 1 channel <p>[30-pin, 32-pin products]</p> <ul style="list-style-type: none"> • CSI: 1 channel/simplified I²C: 1 channel/UART: 1 channel • CSI: 1 channel/simplified I²C: 1 channel/UART: 1 channel • CSI: 1 channel/simplified I²C: 1 channel/UART (UART supporting LIN-bus): 1 channel <p>[36-pin products]</p> <ul style="list-style-type: none"> • CSI: 1 channel/simplified I²C: 1 channel/UART: 1 channel • CSI: 1 channel/simplified I²C: 1 channel/UART: 1 channel • CSI: 2 channels/simplified I²C: 2 channels/UART (UART supporting LIN-bus): 1 channel 											
	I ² C bus	–	1 channel	1 channel								
Multiplier and divider/multiply-accumulator	<ul style="list-style-type: none"> • 16 bits × 16 bits = 32 bits (Unsigned or signed) • 32 bits ÷ 32 bits = 32 bits (Unsigned) • 16 bits × 16 bits + 32 bits = 32 bits (Unsigned or signed) 											
DMA controller	2 channels											
Vectored interrupt sources	Internal	23	24	24	27	27	27	27	27	27	27	27
	External	3	5	5	6	6	6	6	6	6	6	6
Key interrupt	–											
Reset	<ul style="list-style-type: none"> • Reset by <u>RESET</u> pin • Internal reset by watchdog timer • Internal reset by power-on-reset • Internal reset by voltage detector • Internal reset by illegal instruction execution ^{Note} • Internal reset by RAM parity error • Internal reset by illegal-memory access 											
Power-on-reset circuit	<ul style="list-style-type: none"> • Power-on-reset: 1.51 V (TYP.) • Power-down-reset: 1.50 V (TYP.) 											
Voltage detector	<ul style="list-style-type: none"> • Rising edge : 1.67 V to 4.06 V (14 stages) • Falling edge : 1.63 V to 3.98 V (14 stages) 											
On-chip debug function	Provided											
Power supply voltage	$V_{DD} = 1.6 \text{ to } 5.5 \text{ V}$ ($T_A = -40 \text{ to } +85^\circ\text{C}$) $V_{DD} = 2.4 \text{ to } 5.5 \text{ V}$ ($T_A = -40 \text{ to } +105^\circ\text{C}$)											
Operating ambient temperature	$T_A = 40 \text{ to } +85^\circ\text{C}$ (A: Consumer applications, D: Industrial applications) $T_A = 40 \text{ to } +105^\circ\text{C}$ (G: Industrial applications)											

Note The illegal instruction is generated when instruction code FFH is executed.

Reset by the illegal instruction execution not issued by emulation with the in-circuit emulator or on-chip debug emulator.

2. The number of PWM outputs varies depending on the setting of channels in use (the number of masters and slaves) (see **6.9.3 Operation as multiple PWM output function** in the RL78/G13 User's Manual).

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Item	80-pin		100-pin		128-pin	
	R5F100Mx	R5F101Mx	R5F100Px	R5F101Px	R5F100Sx	R5F101Sx
Clock output/buzzer output	2		2		2	
	<ul style="list-style-type: none"> • 2.44 kHz, 4.88 kHz, 9.76 kHz, 1.25 MHz, 2.5 MHz, 5 MHz, 10 MHz (Main system clock: $f_{MAIN} = 20$ MHz operation) • 256 Hz, 512 Hz, 1.024 kHz, 2.048 kHz, 4.096 kHz, 8.192 kHz, 16.384 kHz, 32.768 kHz (Subsystem clock: $f_{SUB} = 32.768$ kHz operation) 					
8/10-bit resolution A/D converter	17 channels		20 channels		26 channels	
Serial interface	[80-pin, 100-pin, 128-pin products]		<ul style="list-style-type: none"> • CSI: 2 channels/simplified I²C: 2 channels/UART: 1 channel • CSI: 2 channels/simplified I²C: 2 channels/UART: 1 channel • CSI: 2 channels/simplified I²C: 2 channels/UART (UART supporting LIN-bus): 1 channel • CSI: 2 channels/simplified I²C: 2 channels/UART: 1 channel 			
I ² C bus	2 channels		2 channels		2 channels	
Multiplier and divider/multiply-accumulator	<ul style="list-style-type: none"> • $16 \text{ bits} \times 16 \text{ bits} = 32 \text{ bits}$ (Unsigned or signed) • $32 \text{ bits} \div 32 \text{ bits} = 32 \text{ bits}$ (Unsigned) • $16 \text{ bits} \times 16 \text{ bits} + 32 \text{ bits} = 32 \text{ bits}$ (Unsigned or signed) 					
DMA controller	4 channels					
Vectorized interrupt sources	Internal	37		37		41
	External	13		13		13
Key interrupt	8		8		8	
Reset	<ul style="list-style-type: none"> • Reset by $\overline{\text{RESET}}$ pin • Internal reset by watchdog timer • Internal reset by power-on-reset • Internal reset by voltage detector • Internal reset by illegal instruction execution ^{Note} • Internal reset by RAM parity error • Internal reset by illegal-memory access 					
Power-on-reset circuit	<ul style="list-style-type: none"> • Power-on-reset: 1.51 V (TYP.) • Power-down-reset: 1.50 V (TYP.) 					
Voltage detector	<ul style="list-style-type: none"> • Rising edge : 1.67 V to 4.06 V (14 stages) • Falling edge : 1.63 V to 3.98 V (14 stages) 					
On-chip debug function	Provided					
Power supply voltage	$V_{DD} = 1.6$ to 5.5 V ($T_A = -40$ to $+85^\circ\text{C}$) $V_{DD} = 2.4$ to 5.5 V ($T_A = -40$ to $+105^\circ\text{C}$)					
Operating ambient temperature	$T_A = 40$ to $+85^\circ\text{C}$ (A: Consumer applications, D: Industrial applications) $T_A = 40$ to $+105^\circ\text{C}$ (G: Industrial applications)					

Note The illegal instruction is generated when instruction code FFH is executed.

Reset by the illegal instruction execution not issued by emulation with the in-circuit emulator or on-chip debug emulator.

<R>

($T_A = -40$ to $+85^\circ\text{C}$, $1.6 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$, $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$) (4/5)

Items	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Output voltage, high	V _{OH1}	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147	4.0 V $\leq EV_{DD0} \leq 5.5 \text{ V}$, I _{OH1} = -10.0 mA	EV _{DD0} – 1.5		V
			4.0 V $\leq EV_{DD0} \leq 5.5 \text{ V}$, I _{OH1} = -3.0 mA	EV _{DD0} – 0.7		V
			2.7 V $\leq EV_{DD0} \leq 5.5 \text{ V}$, I _{OH1} = -2.0 mA	EV _{DD0} – 0.6		V
			1.8 V $\leq EV_{DD0} \leq 5.5 \text{ V}$, I _{OH1} = -1.5 mA	EV _{DD0} – 0.5		V
			1.6 V $\leq EV_{DD0} < 5.5 \text{ V}$, I _{OH1} = -1.0 mA	EV _{DD0} – 0.5		V
	V _{OH2}	P20 to P27, P150 to P156	1.6 V $\leq V_{DD} \leq 5.5 \text{ V}$, I _{OH2} = -100 μA	V _{DD} – 0.5		V
Output voltage, low	V _{OL1}	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147	4.0 V $\leq EV_{DD0} \leq 5.5 \text{ V}$, I _{OL1} = 20 mA		1.3	V
			4.0 V $\leq EV_{DD0} \leq 5.5 \text{ V}$, I _{OL1} = 8.5 mA		0.7	V
			2.7 V $\leq EV_{DD0} \leq 5.5 \text{ V}$, I _{OL1} = 3.0 mA		0.6	V
			2.7 V $\leq EV_{DD0} \leq 5.5 \text{ V}$, I _{OL1} = 1.5 mA		0.4	V
			1.8 V $\leq EV_{DD0} \leq 5.5 \text{ V}$, I _{OL1} = 0.6 mA		0.4	V
			1.6 V $\leq EV_{DD0} < 5.5 \text{ V}$, I _{OL1} = 0.3 mA		0.4	V
	V _{OL2}	P20 to P27, P150 to P156	1.6 V $\leq V_{DD} \leq 5.5 \text{ V}$, I _{OL2} = 400 μA		0.4	V
	V _{OL3}	P60 to P63	4.0 V $\leq EV_{DD0} \leq 5.5 \text{ V}$, I _{OL3} = 15.0 mA		2.0	V
			4.0 V $\leq EV_{DD0} \leq 5.5 \text{ V}$, I _{OL3} = 5.0 mA		0.4	V
			2.7 V $\leq EV_{DD0} \leq 5.5 \text{ V}$, I _{OL3} = 3.0 mA		0.4	V
			1.8 V $\leq EV_{DD0} \leq 5.5 \text{ V}$, I _{OL3} = 2.0 mA		0.4	V
			1.6 V $\leq EV_{DD0} < 5.5 \text{ V}$, I _{OL3} = 1.0 mA		0.4	V

Caution P00, P02 to P04, P10 to P15, P17, P43 to P45, P50, P52 to P55, P71, P74, P80 to P82, P96, and P142 to P144 do not output high level in N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

2.3.2 Supply current characteristics

(1) Flash ROM: 16 to 64 KB of 20- to 64-pin products

 $(T_A = -40$ to $+85^\circ\text{C}$, $1.6 \text{ V} \leq EV_{DD0} \leq V_{DD} \leq 5.5 \text{ V}$, $V_{ss} = EV_{ss0} = 0 \text{ V}$) (1/2)

Parameter	Symbol	Conditions				MIN.	TYP.	MAX.	Unit
Supply current ^{Note 1}	I_{DD1}	Operating mode HS (high-speed main) mode ^{Note 5}	$f_{IH} = 32 \text{ MHz}^{\text{Note 3}}$	Basic operation	$V_{DD} = 5.0 \text{ V}$		2.1		mA
					$V_{DD} = 3.0 \text{ V}$		2.1		mA
			$f_{IH} = 24 \text{ MHz}^{\text{Note 3}}$	Normal operation	$V_{DD} = 5.0 \text{ V}$		4.6	7.0	mA
					$V_{DD} = 3.0 \text{ V}$		4.6	7.0	mA
			$f_{IH} = 16 \text{ MHz}^{\text{Note 3}}$	Normal operation	$V_{DD} = 5.0 \text{ V}$		2.7	4.0	mA
					$V_{DD} = 3.0 \text{ V}$		2.7	4.0	mA
		LS (low-speed main) mode ^{Note 5}	$f_{IH} = 8 \text{ MHz}^{\text{Note 3}}$	Normal operation	$V_{DD} = 3.0 \text{ V}$		1.2	1.8	mA
					$V_{DD} = 2.0 \text{ V}$		1.2	1.8	mA
		LV (low-voltage main) mode ^{Note 5}	$f_{IH} = 4 \text{ MHz}^{\text{Note 3}}$	Normal operation	$V_{DD} = 3.0 \text{ V}$		1.2	1.7	mA
					$V_{DD} = 2.0 \text{ V}$		1.2	1.7	mA
		HS (high-speed main) mode ^{Note 5}	$f_{MX} = 20 \text{ MHz}^{\text{Note 2}}, V_{DD} = 5.0 \text{ V}$	Normal operation	Square wave input		3.0	4.6	mA
					Resonator connection		3.2	4.8	mA
			$f_{MX} = 20 \text{ MHz}^{\text{Note 2}}, V_{DD} = 3.0 \text{ V}$	Normal operation	Square wave input		3.0	4.6	mA
					Resonator connection		3.2	4.8	mA
			$f_{MX} = 10 \text{ MHz}^{\text{Note 2}}, V_{DD} = 5.0 \text{ V}$	Normal operation	Square wave input		1.9	2.7	mA
					Resonator connection		1.9	2.7	mA
			$f_{MX} = 10 \text{ MHz}^{\text{Note 2}}, V_{DD} = 3.0 \text{ V}$	Normal operation	Square wave input		1.9	2.7	mA
					Resonator connection		1.9	2.7	mA
		LS (low-speed main) mode ^{Note 5}	$f_{MX} = 8 \text{ MHz}^{\text{Note 2}}, V_{DD} = 3.0 \text{ V}$	Normal operation	Square wave input		1.1	1.7	mA
					Resonator connection		1.1	1.7	mA
			$f_{MX} = 8 \text{ MHz}^{\text{Note 2}}, V_{DD} = 2.0 \text{ V}$	Normal operation	Square wave input		1.1	1.7	mA
					Resonator connection		1.1	1.7	mA
		Subsystem clock operation	$f_{SUB} = 32.768 \text{ kHz}$ ^{Note 4} $T_A = -40^\circ\text{C}$	Normal operation	Square wave input		4.1	4.9	μA
					Resonator connection		4.2	5.0	μA
			$f_{SUB} = 32.768 \text{ kHz}$ ^{Note 4} $T_A = +25^\circ\text{C}$	Normal operation	Square wave input		4.1	4.9	μA
					Resonator connection		4.2	5.0	μA
			$f_{SUB} = 32.768 \text{ kHz}$ ^{Note 4} $T_A = +50^\circ\text{C}$	Normal operation	Square wave input		4.2	5.5	μA
					Resonator connection		4.3	5.6	μA
			$f_{SUB} = 32.768 \text{ kHz}$ ^{Note 4} $T_A = +70^\circ\text{C}$	Normal operation	Square wave input		4.3	6.3	μA
					Resonator connection		4.4	6.4	μA
			$f_{SUB} = 32.768 \text{ kHz}$ ^{Note 4} $T_A = +85^\circ\text{C}$	Normal operation	Square wave input		4.6	7.7	μA
					Resonator connection		4.7	7.8	μA

(Notes and Remarks are listed on the next page.)

Notes 1. Total current flowing into V_{DD} and EV_{DD0} , including the input leakage current flowing when the level of the input pin is fixed to V_{DD} , EV_{DD0} or V_{SS} , EV_{SS0} . The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.

2. When high-speed on-chip oscillator and subsystem clock are stopped.
3. When high-speed system clock and subsystem clock are stopped.
4. When high-speed on-chip oscillator and high-speed system clock are stopped. When $\text{AMPHS1} = 1$ (Ultra-low power consumption oscillation). However, not including the current flowing into the RTC, 12-bit interval timer, and watchdog timer.
5. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: $2.7 \text{ V} \leq V_{DD} \leq 5.5 \text{ V}$ @ 1 MHz to 32 MHz

$2.4 \text{ V} \leq V_{DD} \leq 5.5 \text{ V}$ @ 1 MHz to 16 MHz

LS (low-speed main) mode: $1.8 \text{ V} \leq V_{DD} \leq 5.5 \text{ V}$ @ 1 MHz to 8 MHz

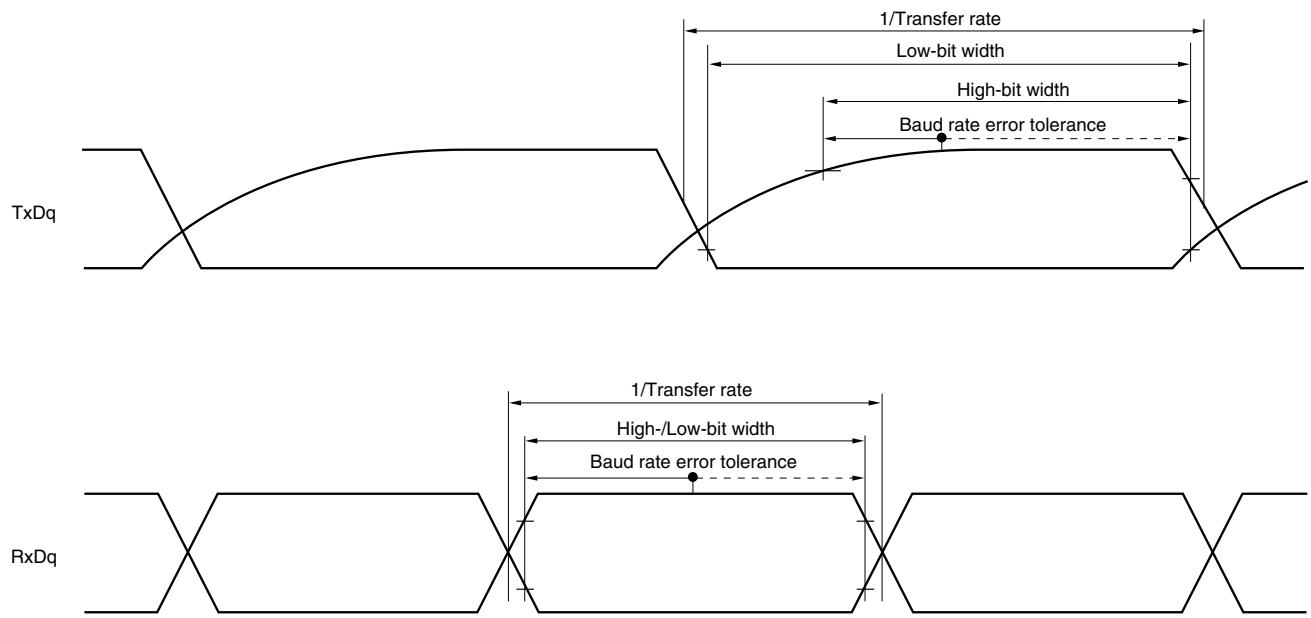
LV (low-voltage main) mode: $1.6 \text{ V} \leq V_{DD} \leq 5.5 \text{ V}$ @ 1 MHz to 4 MHz

Remarks 1. f_{MX} : High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)

2. f_{IH} : High-speed on-chip oscillator clock frequency

3. f_{SUB} : Subsystem clock frequency (XT1 clock oscillation frequency)

4. Except subsystem clock operation, temperature condition of the TYP. value is $T_A = 25^\circ\text{C}$

UART mode bit width (during communication at different potential) (reference)

- Remarks**
1. $R_b[\Omega]$: Communication line (TxDq) pull-up resistance,
 $C_b[F]$: Communication line (TxDq) load capacitance, $V_b[V]$: Communication line voltage
 2. q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 8, 14)
 3. f_{MCK} : Serial array unit operation clock frequency
 (Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn).
 m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))
 4. UART2 cannot communicate at different potential when bit 1 (PIOR1) of peripheral I/O redirection register (PIOR) is 1.

**(8) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output)
(2/3)**

($T_A = -40$ to $+85^\circ\text{C}$, $1.8 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$, $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Slp setup time (to SCKp \uparrow) ^{Note 1}	tsIK1	4.0 V \leq EV _{DD0} \leq 5.5 V, 2.7 V \leq V _b \leq 4.0 V, C _b = 30 pF, R _b = 1.4 k Ω	81		479		479		ns
		2.7 V \leq EV _{DD0} < 4.0 V, 2.3 V \leq V _b \leq 2.7 V, C _b = 30 pF, R _b = 2.7 k Ω	177		479		479		ns
		1.8 V \leq EV _{DD0} < 3.3 V, 1.6 V \leq V _b \leq 2.0 V ^{Note 2} , C _b = 30 pF, R _b = 5.5 k Ω	479		479		479		ns
Slp hold time (from SCKp \uparrow) ^{Note 1}	tKS11	4.0 V \leq EV _{DD0} \leq 5.5 V, 2.7 V \leq V _b \leq 4.0 V, C _b = 30 pF, R _b = 1.4 k Ω	19		19		19		ns
		2.7 V \leq EV _{DD0} < 4.0 V, 2.3 V \leq V _b \leq 2.7 V, C _b = 30 pF, R _b = 2.7 k Ω	19		19		19		ns
		1.8 V \leq EV _{DD0} < 3.3 V, 1.6 V \leq V _b \leq 2.0 V ^{Note 2} , C _b = 30 pF, R _b = 5.5 k Ω	19		19		19		ns
Delay time from SCKp \downarrow to SO _p output ^{Note 1}	tKS01	4.0 V \leq EV _{DD0} \leq 5.5 V, 2.7 V \leq V _b \leq 4.0 V, C _b = 30 pF, R _b = 1.4 k Ω		100		100		100	ns
		2.7 V \leq EV _{DD0} < 4.0 V, 2.3 V \leq V _b \leq 2.7 V, C _b = 30 pF, R _b = 2.7 k Ω		195		195		195	ns
		1.8 V \leq EV _{DD0} < 3.3 V, 1.6 V \leq V _b \leq 2.0 V ^{Note 2} , C _b = 30 pF, R _b = 5.5 k Ω		483		483		483	ns

Notes 1. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.

2. Use it with EV_{DD0} \geq V_b.

Caution Select the TTL input buffer for the Slp pin and the N-ch open drain output (V_{DD} tolerance (When 20- to 52-pin products)/EV_{DD} tolerance (When 64- to 128-pin products)) mode for the SO_p pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

(Remarks are listed on the page after the next page.)

(9) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (slave mode, SCKp... external clock input)

($T_A = -40$ to $+85^\circ\text{C}$, $1.8 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$, $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$) (2/2)

Parameter	Symbol	Conditions	HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp high-/low-level width	t_{KH2} , t_{KL2}	4.0 V $\leq EV_{DD0} \leq 5.5$ V, 2.7 V $\leq V_b \leq 4.0$ V	$t_{KCY2}/2$ – 12		$t_{KCY2}/2$ – 50		$t_{KCY2}/2$ – 50		ns
		2.7 V $\leq EV_{DD0} < 4.0$ V, 2.3 V $\leq V_b \leq 2.7$ V	$t_{KCY2}/2$ – 18		$t_{KCY2}/2$ – 50		$t_{KCY2}/2$ – 50		ns
		1.8 V $\leq EV_{DD0} < 3.3$ V, 1.6 V $\leq V_b \leq 2.0$ V ^{Note 2}	$t_{KCY2}/2$ – 50		$t_{KCY2}/2$ – 50		$t_{KCY2}/2$ – 50		ns
Slp setup time (to SCKp↑) ^{Note 3}	t_{SIK2}	4.0 V $\leq EV_{DD0} \leq 5.5$ V, 2.7 V $\leq V_b \leq 4.0$ V	$1/f_{MCK}$ + 20		$1/f_{MCK}$ + 30		$1/f_{MCK}$ + 30		ns
		2.7 V $\leq EV_{DD0} < 4.0$ V, 2.3 V $\leq V_b \leq 2.7$ V	$1/f_{MCK}$ + 20		$1/f_{MCK}$ + 30		$1/f_{MCK}$ + 30		ns
		1.8 V $\leq EV_{DD0} < 3.3$ V, 1.6 V $\leq V_b \leq 2.0$ V ^{Note 2}	$1/f_{MCK}$ + 30		$1/f_{MCK}$ + 30		$1/f_{MCK}$ + 30		ns
Slp hold time (from SCKp↑) ^{Note 4}	t_{SIS2}		$1/f_{MCK} +$ 31		$1/f_{MCK}$ + 31		$1/f_{MCK}$ + 31		ns
Delay time from SCKp↓ to SOp output ^{Note 5}	t_{KS02}	4.0 V $\leq EV_{DD0} \leq 5.5$ V, 2.7 V $\leq V_b \leq 4.0$ V, $C_b = 30 \text{ pF}$, $R_b = 1.4 \text{ k}\Omega$		$2/f_{MCK}$ + 120		$2/f_{MCK}$ + 573		$2/f_{MCK}$ + 573	ns
		2.7 V $\leq EV_{DD0} < 4.0$ V, 2.3 V $\leq V_b \leq 2.7$ V, $C_b = 30 \text{ pF}$, $R_b = 2.7 \text{ k}\Omega$		$2/f_{MCK}$ + 214		$2/f_{MCK}$ + 573		$2/f_{MCK}$ + 573	ns
		1.8 V $\leq EV_{DD0} < 3.3$ V, 1.6 V $\leq V_b \leq 2.0$ V ^{Note 2} , $C_b = 30 \text{ pF}$, $R_b = 5.5 \text{ k}\Omega$		$2/f_{MCK}$ + 573		$2/f_{MCK}$ + 573		$2/f_{MCK}$ + 573	ns

Notes 1. Transfer rate in the SNOOZE mode : MAX. 1 Mbps

2. Use it with $EV_{DD0} \geq V_b$.
3. When $DAP_{mn} = 0$ and $CKP_{mn} = 0$, or $DAP_{mn} = 1$ and $CKP_{mn} = 1$. The Slp setup time becomes “to SCKp↑” when $DAP_{mn} = 0$ and $CKP_{mn} = 1$, or $DAP_{mn} = 1$ and $CKP_{mn} = 0$.
4. When $DAP_{mn} = 0$ and $CKP_{mn} = 0$, or $DAP_{mn} = 1$ and $CKP_{mn} = 1$. The Slp hold time becomes “from SCKp↑” when $DAP_{mn} = 0$ and $CKP_{mn} = 1$, or $DAP_{mn} = 1$ and $CKP_{mn} = 0$.
5. When $DAP_{mn} = 0$ and $CKP_{mn} = 0$, or $DAP_{mn} = 1$ and $CKP_{mn} = 1$. The delay time to SOp output becomes “from SCKp↑” when $DAP_{mn} = 0$ and $CKP_{mn} = 1$, or $DAP_{mn} = 1$ and $CKP_{mn} = 0$.

Caution Select the TTL input buffer for the Slp pin and the N-ch open drain output (V_{DD} tolerance (for the 20- to 52-pin products)/ EV_{DD} tolerance (for the 64- to 128-pin products)) mode for the SOp pin and SCKp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL} , see the DC characteristics with TTL input buffer selected.

(Remarks are listed on the next page.)

- (3) When reference voltage (+) = V_{DD} ($\text{ADREFP1} = 0$, $\text{ADREFP0} = 0$), reference voltage (-) = V_{SS} ($\text{ADREFM} = 0$), target pin : ANI0 to ANI14, ANI16 to ANI26, internal reference voltage, and temperature sensor output voltage

($T_A = -40$ to $+85^\circ\text{C}$, $1.6 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$, $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$, Reference voltage (+) = V_{DD} , Reference voltage (-) = V_{SS})

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error ^{Note 1}	AINL	10-bit resolution	1.8 V $\leq V_{DD} \leq 5.5 \text{ V}$		1.2	± 7.0	LSB
			1.6 V $\leq V_{DD} \leq 5.5 \text{ V}$ Note 3		1.2	± 10.5	LSB
Conversion time	t _{CONV}	10-bit resolution Target pin: ANI0 to ANI14, ANI16 to ANI26	3.6 V $\leq V_{DD} \leq 5.5 \text{ V}$	2.125		39	μs
			2.7 V $\leq V_{DD} \leq 5.5 \text{ V}$	3.1875		39	μs
			1.8 V $\leq V_{DD} \leq 5.5 \text{ V}$	17		39	μs
			1.6 V $\leq V_{DD} \leq 5.5 \text{ V}$	57		95	μs
Conversion time	t _{CONV}	10-bit resolution Target pin: Internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	3.6 V $\leq V_{DD} \leq 5.5 \text{ V}$	2.375		39	μs
			2.7 V $\leq V_{DD} \leq 5.5 \text{ V}$	3.5625		39	μs
			2.4 V $\leq V_{DD} \leq 5.5 \text{ V}$	17		39	μs
Zero-scale error ^{Notes 1, 2}	E _{ZS}	10-bit resolution	1.8 V $\leq V_{DD} \leq 5.5 \text{ V}$			± 0.60	%FSR
			1.6 V $\leq V_{DD} \leq 5.5 \text{ V}$ Note 3			± 0.85	%FSR
Full-scale error ^{Notes 1, 2}	E _{FS}	10-bit resolution	1.8 V $\leq V_{DD} \leq 5.5 \text{ V}$			± 0.60	%FSR
			1.6 V $\leq V_{DD} \leq 5.5 \text{ V}$ Note 3			± 0.85	%FSR
Integral linearity error ^{Note 1}	ILE	10-bit resolution	1.8 V $\leq V_{DD} \leq 5.5 \text{ V}$			± 4.0	LSB
			1.6 V $\leq V_{DD} \leq 5.5 \text{ V}$ Note 3			± 6.5	LSB
Differential linearity error ^{Note 1}	DLE	10-bit resolution	1.8 V $\leq V_{DD} \leq 5.5 \text{ V}$			± 2.0	LSB
			1.6 V $\leq V_{DD} \leq 5.5 \text{ V}$ Note 3			± 2.5	LSB
Analog input voltage	V _{AIN}	ANI0 to ANI14		0		V_{DD}	V
		ANI16 to ANI26		0		EV_{DD0}	V
		Internal reference voltage (2.4 V $\leq V_{DD} \leq 5.5 \text{ V}$, HS (high-speed main) mode)		V_{BGR} ^{Note 4}			V
		Temperature sensor output voltage (2.4 V $\leq V_{DD} \leq 5.5 \text{ V}$, HS (high-speed main) mode)		V_{TMPS25} ^{Note 4}			V

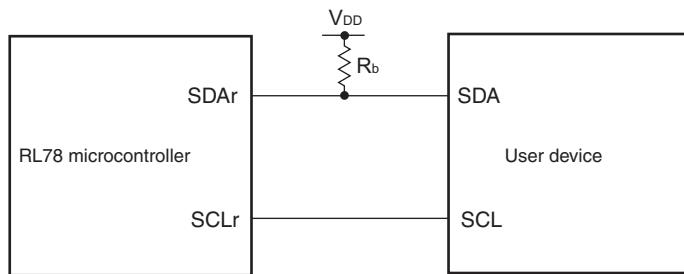
- Notes**
- Excludes quantization error ($\pm 1/2$ LSB).
 - This value is indicated as a ratio (%FSR) to the full-scale value.
 - When the conversion time is set to 57 μs (min.) and 95 μs (max.).
 - Refer to **2.6.2 Temperature sensor/internal reference voltage characteristics**.

(TA = -40 to +105°C, 2.4 V ≤ EV_{DD0} = EV_{DD1} ≤ V_{DD} ≤ 5.5 V, V_{SS} = EV_{SS0} = EV_{SS1} = 0 V) (5/5)

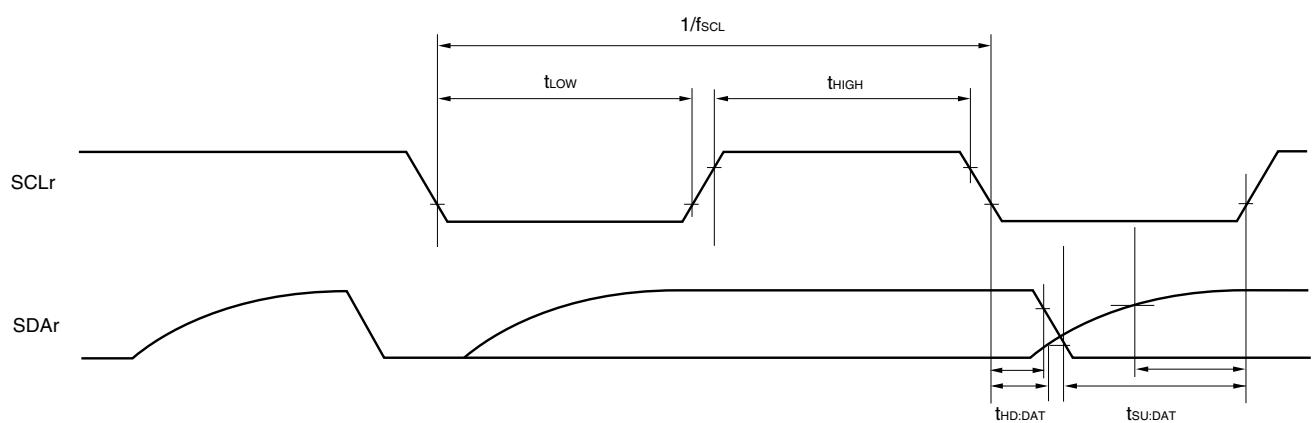
Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Input leakage current, high	I _{LH1}	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147		V _I = EV _{DD0}		1	μA
	I _{LH2}	P20 to P27, P137, P150 to P156, RESET		V _I = V _{DD}		1	μA
	I _{LH3}	P121 to P124 (X1, X2, XT1, XT2, EXCLK, EXCLKS)		V _I = V _{DD}	In input port or external clock input	1	μA
						10	μA
Input leakage current, low	I _{LIL1}	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147		V _I = EV _{SS0}		-1	μA
	I _{LIL2}	P20 to P27, P137, P150 to P156, RESET		V _I = V _{SS}		-1	μA
	I _{LIL3}	P121 to P124 (X1, X2, XT1, XT2, EXCLK, EXCLKS)		V _I = V _{SS}	In input port or external clock input	-1	μA
						-10	μA
On-chip pll-up resistance	R _U	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147		V _I = EV _{SS0} , In input port		10	20
						100	kΩ

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

Simplified I²C mode connection diagram (during communication at same potential)



Simplified I²C mode serial transfer timing (during communication at same potential)



Remarks 1. R_b[Ω]:Communication line (SDAr) pull-up resistance, C_b[F]: Communication line (SDAr, SCLr) load capacitance

2. r: IIC number (r = 00, 01, 10, 11, 20, 21, 30, 31), g: PIM number (g = 0, 1, 4, 5, 8, 14), h: POM number (g = 0, 1, 4, 5, 7 to 9, 14)

3. f_{MCK}: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number (m = 0, 1), n: Channel number (n = 0 to 3), mn = 00 to 03, 10 to 13)

- (2) When reference voltage (+) = $AV_{REFP}/ANI0$ (ADREFP1 = 0, ADREFP0 = 1), reference voltage (-) = $AV_{REFM}/ANI1$ (ADREFM = 1), target pin : ANI16 to ANI26

(TA = -40 to +105°C, 2.4 V ≤ EV_{DD0} = EV_{DD1} ≤ V_{DD} ≤ 5.5 V, 2.4 V ≤ AV_{REFP} ≤ V_{DD} ≤ 5.5 V, V_{SS} = EV_{VSS0} = EV_{VSS1} = 0 V, Reference voltage (+) = AV_{REFP}, Reference voltage (-) = AV_{REFM} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error ^{Note 1}	AINL	10-bit resolution EV _{DD0} ≤ AV _{REFP} = V _{DD} ^{Notes 3, 4}	2.4 V ≤ AV _{REFP} ≤ 5.5 V		1.2	±5.0	LSB
Conversion time	t _{CONV}	10-bit resolution Target pin : ANI16 to ANI26	3.6 V ≤ V _{DD} ≤ 5.5 V	2.125		39	μs
			2.7 V ≤ V _{DD} ≤ 5.5 V	3.1875		39	μs
			2.4 V ≤ V _{DD} ≤ 5.5 V	17		39	μs
Zero-scale error ^{Notes 1, 2}	E _{ZS}	10-bit resolution EV _{DD0} ≤ AV _{REFP} = V _{DD} ^{Notes 3, 4}	2.4 V ≤ AV _{REFP} ≤ 5.5 V			±0.35	%FSR
Full-scale error ^{Notes 1, 2}	E _{FS}	10-bit resolution EV _{DD0} ≤ AV _{REFP} = V _{DD} ^{Notes 3, 4}	2.4 V ≤ AV _{REFP} ≤ 5.5 V			±0.35	%FSR
Integral linearity error ^{Note 1}	ILE	10-bit resolution EV _{DD0} ≤ AV _{REFP} = V _{DD} ^{Notes 3, 4}	2.4 V ≤ AV _{REFP} ≤ 5.5 V			±3.5	LSB
Differential linearity error <small>Note 1</small>	DLE	10-bit resolution EV _{DD0} ≤ AV _{REFP} = V _{DD} ^{Notes 3, 4}	2.4 V ≤ AV _{REFP} ≤ 5.5 V			±2.0	LSB
Analog input voltage	V _{AiN}	ANI16 to ANI26		0		AV _{REFP} and EV _{DD0}	V

Notes 1. Excludes quantization error (±1/2 LSB).

2. This value is indicated as a ratio (%FSR) to the full-scale value.

3. When AV_{REFP} < V_{DD}, the MAX. values are as follows.

Overall error: Add ±1.0 LSB to the MAX. value when AV_{REFP} = V_{DD}.

Zero-scale error/Full-scale error: Add ±0.05%FSR to the MAX. value when AV_{REFP} = V_{DD}.

Integral linearity error/ Differential linearity error: Add ±0.5 LSB to the MAX. value when AV_{REFP} = V_{DD}.

4. When AV_{REFP} < EV_{DD0} ≤ V_{DD}, the MAX. values are as follows.

Overall error: Add ±4.0 LSB to the MAX. value when AV_{REFP} = V_{DD}.

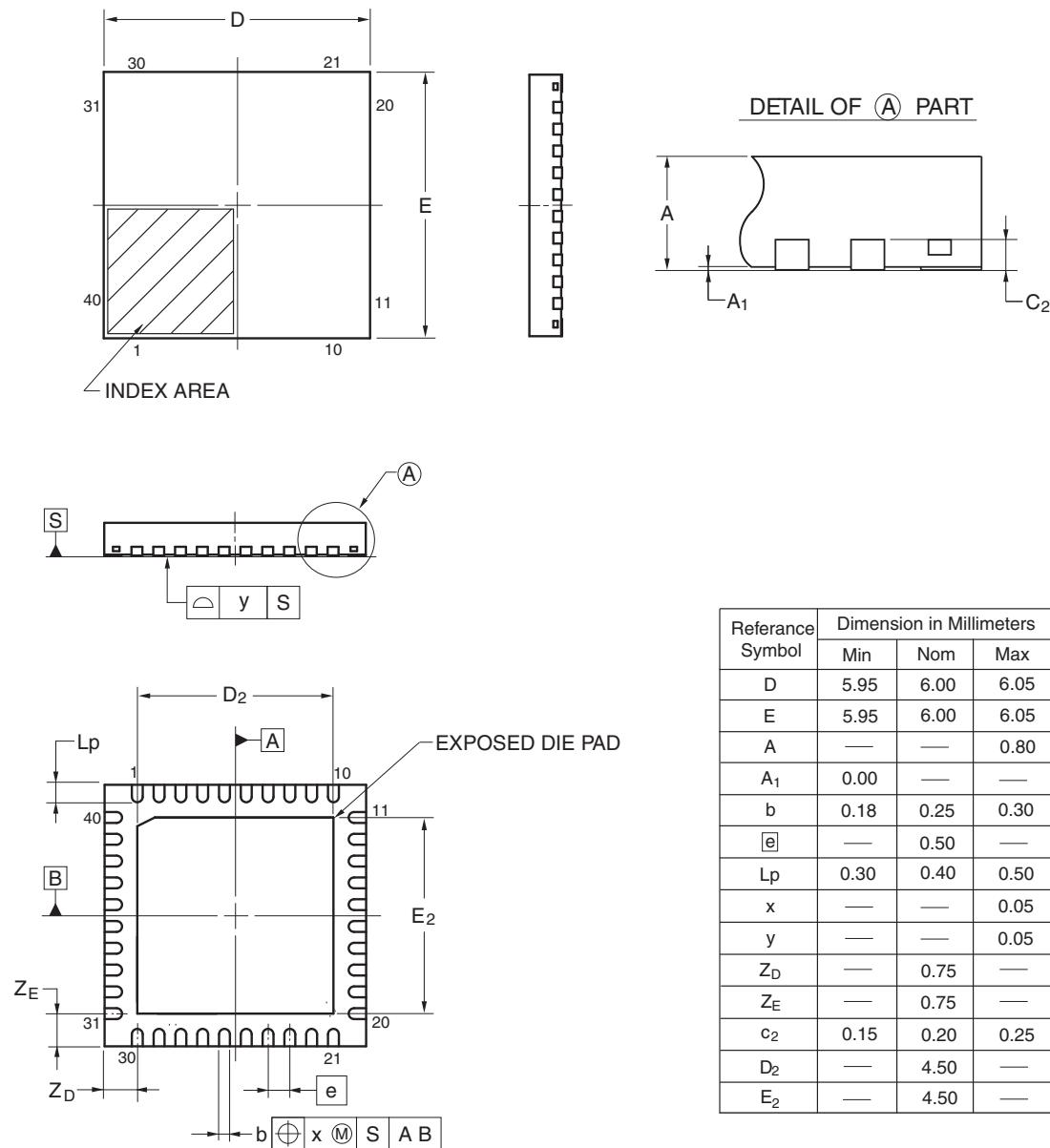
Zero-scale error/Full-scale error: Add ±0.20%FSR to the MAX. value when AV_{REFP} = V_{DD}.

Integral linearity error/ Differential linearity error: Add ±2.0 LSB to the MAX. value when AV_{REFP} = V_{DD}.

4.7 40-pin Products

R5F100EAANA, R5F100ECANA, R5F100EDANA, R5F100EEANA, R5F100EFANA, R5F100EGANA, R5F100EHANA
 R5F101EAANA, R5F101ECANA, R5F101EDANA, R5F101EEANA, R5F101EFANA, R5F101EGANA, R5F101EHANA
 R5F100EADNA, R5F100ECDNA, R5F100EDDNA, R5F100EEDNA, R5F100EFDNA, R5F100EGDNA,
 R5F100EHDNA
 R5F101EADNA, R5F101ECDNA, R5F101EDDNA, R5F101EEDNA, R5F101EFDNA, R5F101EGDNA,
 R5F101EHDNA
 R5F100EAGNA, R5F100ECGNA, R5F100EDGNA, R5F100EEGNA, R5F100EFGNA, R5F100EGGNA,
 R5F100EHGNA

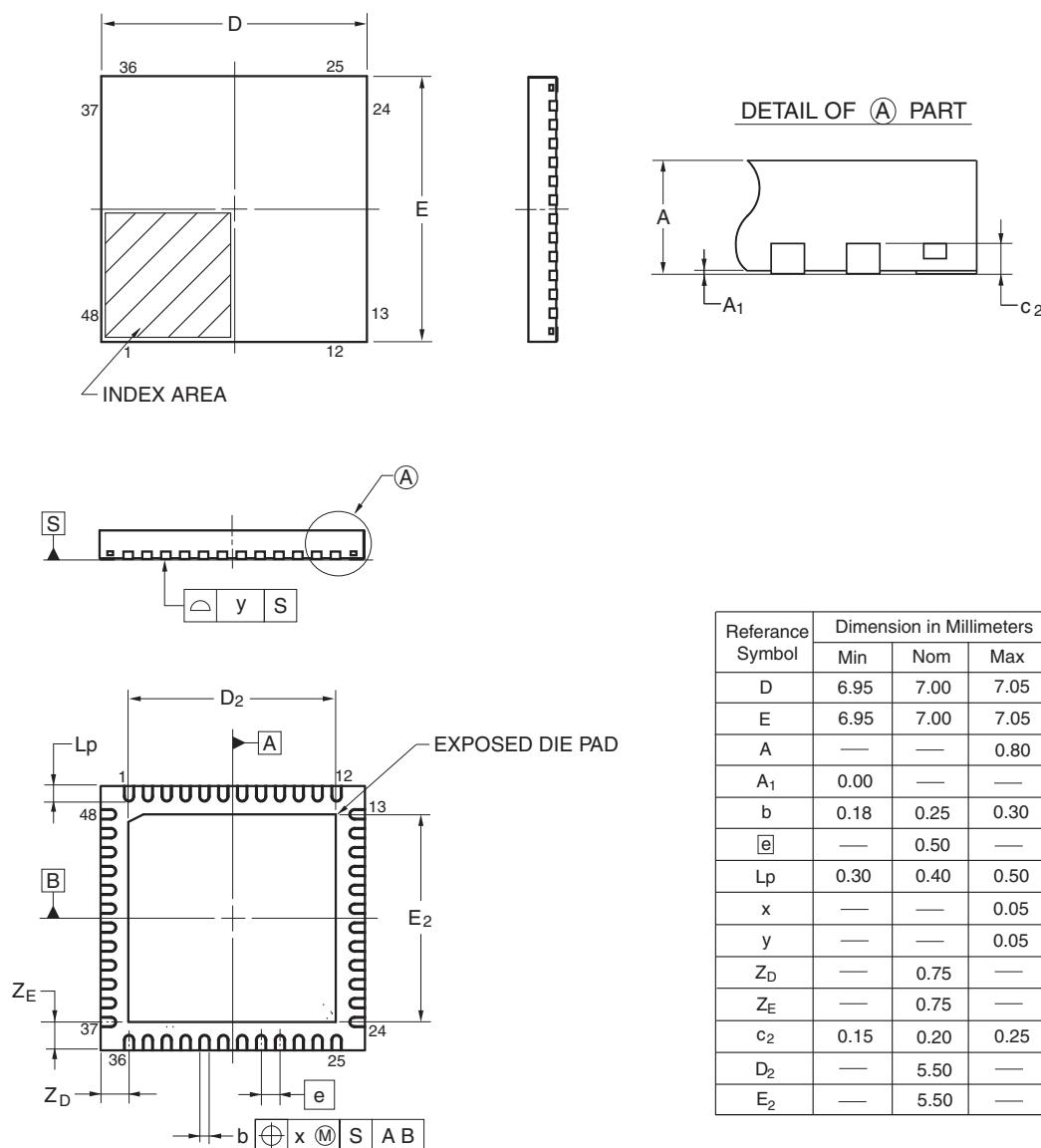
JEITA Package code	RENESAS code	Previous code	MASS (TYP) [g]
P-HWQFN40-6x6-0.50	PWQN0040KC-A	P40K8-50-4B4-5	0.09



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R5F100GAANA, R5F100GCANA, R5F100GDANA, R5F100GEANA, R5F100GFANA, R5F100GGANA,
 R5F100GHANA, R5F100GJANA, R5F100GKANA, R5F100GLANA
 R5F101GAANA, R5F101GCANA, R5F101GDANA, R5F101GEANA, R5F101GFANA, R5F101GGANA,
 R5F101GHANA, R5F101GJANA, R5F101GKANA, R5F101GLANA
 R5F100GADNA, R5F100GCDNA, R5F100GDDNA, R5F100GEDNA, R5F100GFDNA, R5F100GGDNA,
 R5F100GHDNA, R5F100GJDNA, R5F100GKDNA, R5F100GLDNA
 R5F101GADNA, R5F101GCDNA, R5F101GDDNA, R5F101GEDNA, R5F101GFDNA, R5F101GGDNA,
 R5F101GHDNA, R5F101GJDNA, R5F101GKDNA, R5F101GLDNA
 R5F100GAGNA, R5F100GCGNA, R5F100GDGNA, R5F100GEGNA, R5F100GFGNA, R5F100GGGNA,
 R5F100GHGNA, R5F100GJGNA

JEITA Package code	RENESAS code	Previous code	MASS(TYP.)[g]
P-HWQFN48-7x7-0.50	PWQN0048KB-A	48PQN-A P48K8-50-5B4-6	0.13

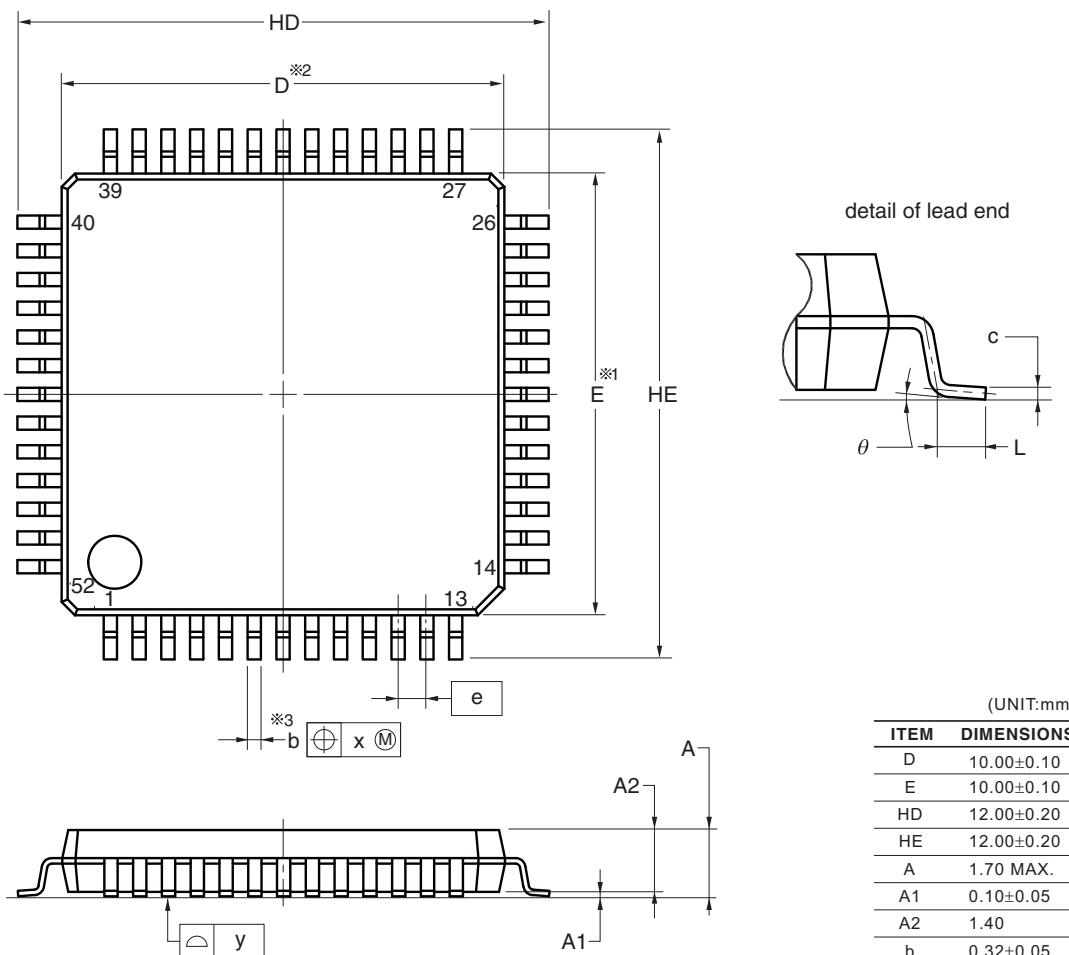


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4.10 52-pin Products

R5F100JCAFA, R5F100JDAFA, R5F100JEAF, R5F100JFAFA, R5F100JGAF, R5F100JHAF, R5F100JJAF,
 R5F100JKAF, R5F100JLAF
 R5F101JCAFA, R5F101JDAFA, R5F101JEAF, R5F101JFAFA, R5F101JGAF, R5F101JHAF, R5F101JJAF,
 R5F101JKAF, R5F101JLAF
 R5F100JCDFA, R5F100JDDFA, R5F100JEDFA, R5F100JFDFA, R5F100JGDFA, R5F100JHDFA, R5F100JJDF,
 R5F100JKDFA, R5F100JLDFA
 R5F101JCDFA, R5F101JDDFA, R5F101JEDFA, R5F101JFDFA, R5F101JGDFA, R5F101JHDFA, R5F101JJDF,
 R5F101JKDFA, R5F101JLDFA
 R5F100JCGFA, R5F100JDGFA, R5F100JEGFA, R5F100JFGFA, R5F100JGGFA, R5F100JHGFA, R5F100JJGFA

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-LQFP52-10x10-0.65	PLQP0052JA-A	P52GB-65-GBS-1	0.3



NOTE

1. Dimensions “*1” and “*2” do not include mold flash.
2. Dimension “*3” does not include trim offset.

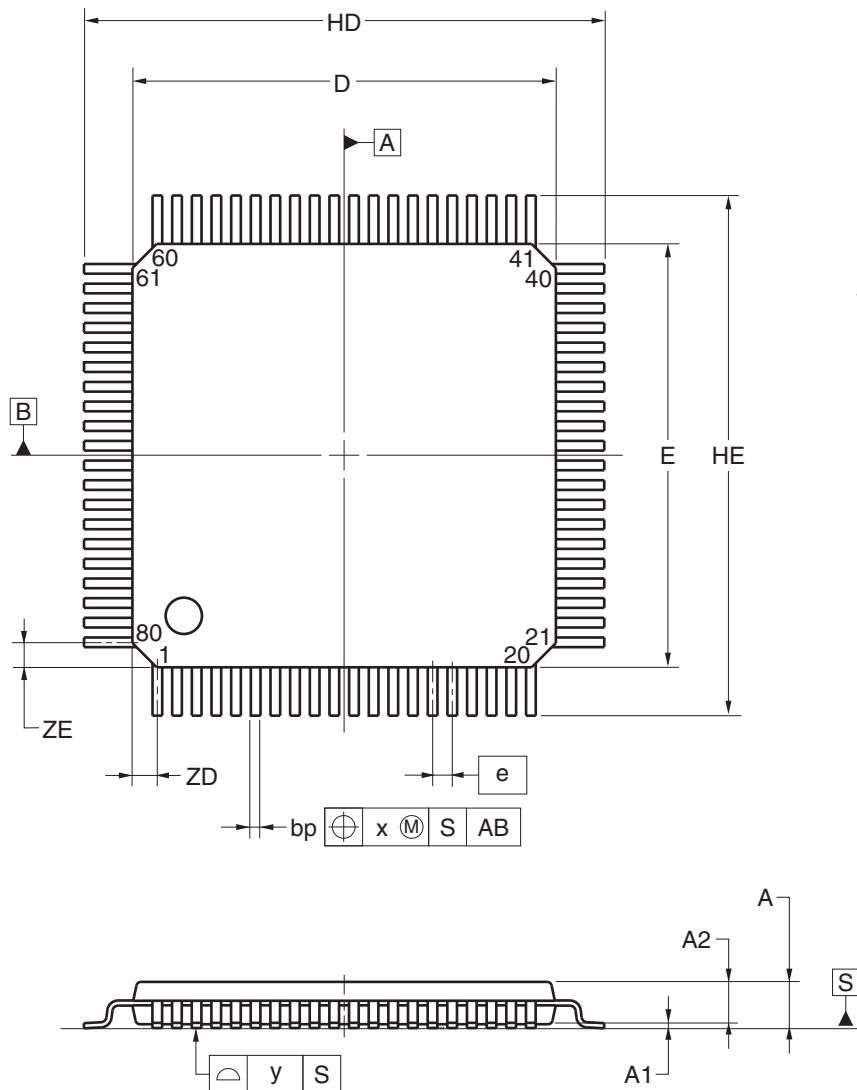
(UNIT:mm)	
ITEM	DIMENSIONS
D	10.00±0.10
E	10.00±0.10
HD	12.00±0.20
HE	12.00±0.20
A	1.70 MAX.
A1	0.10±0.05
A2	1.40
b	0.32±0.05
c	0.145±0.055
L	0.50±0.15
θ	0° to 8°
e	0.65
x	0.13
y	0.10

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4.12 80-pin Products

R5F100MFAFA, R5F100MGAFA, R5F100MHAFA, R5F100MJAFA, R5F100MKAFA, R5F100MLAFA
 R5F101MFAFA, R5F101MGAFA, R5F101MHAFA, R5F101MJAFA, R5F101MKAFA, R5F101MLAFA
 R5F100MFDFA, R5F100MGDFA, R5F100MHDFA, R5F100MJ DFA, R5F100MK DFA, R5F100ML DFA
 R5F101MFDFA, R5F101MGDFA, R5F101MHDFA, R5F101MJ DFA, R5F101MK DFA, R5F101ML DFA
 R5F100MFGFA, R5F100MGGFA, R5F100MHGFA, R5F100MJGFA

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP) [g]
P-LQFP80-14x14-0.65	PLQP0080JB-E	P80GC-65-UBT-2	0.69



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.80	14.00	14.20
E	13.80	14.00	14.20
HD	17.00	17.20	17.40
HE	17.00	17.20	17.40
A	—	—	1.70
A1	0.05	0.125	0.20
A2	1.35	1.40	1.45
A3	—	0.25	—
bp	0.26	0.32	0.38
c	0.10	0.145	0.20
L	—	0.80	—
Lp	0.736	0.886	1.036
L1	1.40	1.60	1.80
θ	0°	3°	8°
e	—	0.65	—
x	—	—	0.13
y	—	—	0.10
ZD	—	0.825	—
ZE	—	0.825	—

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R5F100PFAFA, R5F100PGAFA, R5F100PHAFA, R5F100PJAFA, R5F100PKAFA, R5F100PLAFA
 R5F101PFAFA, R5F101PGAFA, R5F101PHAFA, R5F101PJAFA, R5F101PKAFA, R5F101PLAFA
 R5F100PFDFA, R5F100PGDFA, R5F100PHDFA, R5F100PJ DFA, R5F100PK DFA, R5F100PL DFA
 R5F101PFDFA, R5F101PGDFA, R5F101PHDFA, R5F101PJ DFA, R5F101PK DFA, R5F101PL DFA
 R5F100PFGFA, R5F100PGGFA, R5F100PHGFA, R5F100PJGFA

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-LQFP100-14x20-0.65	PLQP0100JC-A	P100GF-65-GBN-1	0.92

